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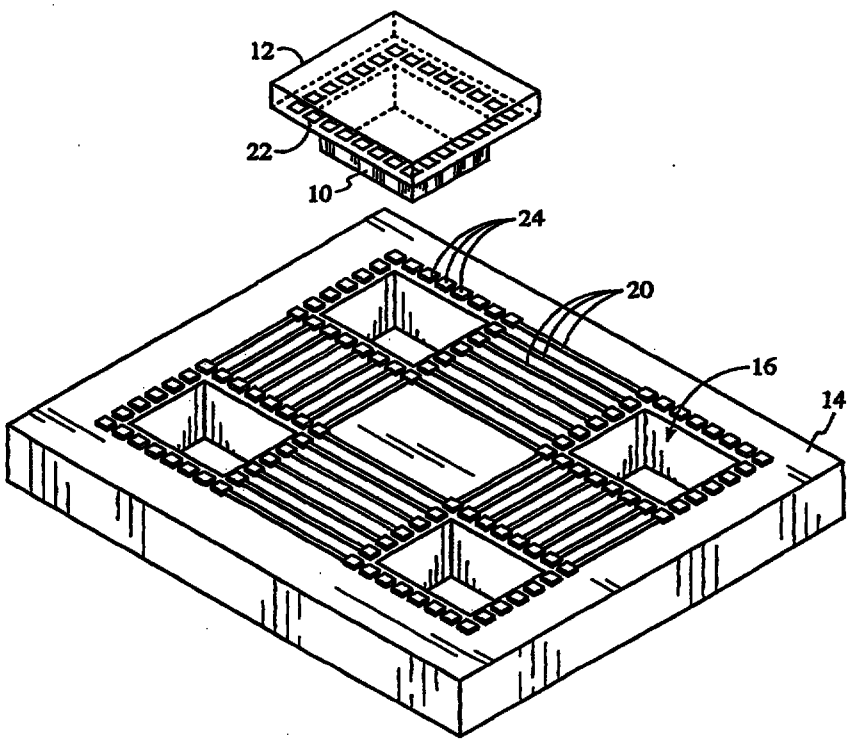
(54) Title: A SYSTEM AND METHOD FOR PACKAGING INTEGRATED CIRCUITS

(57) Abstract

A system and method for efficiently interconnecting a plurality of ICs, thereby improving the electrical performance of the overall system. In one embodiment of the system of the present invention, a plurality of carriers (12) corresponds to a plurality of ICs (10), and a board (14) has a plurality of board regions (16) for receiving the plurality of ICs (10). In one embodiment of the method of the present invention, a carrier (12) is provided for each IC (10) in a complex IC. A board (14) having openings (16) is provided, and the ICs (10) are fitted into the board openings (16) with the carriers (12) mounted thereto.